ABSTRACT

PREPREG AND LAMINATE AND PRINTED WIRING BOARD USING THE SAME

A paper base material is impregnated in advance with a composition containing an alkoxysilane derivative and/or condensate of an alkoxysilane derivative. The paper base material is then impregnated with a thermosetting resin composition containing a phenolic resin, followed by heating and drying to obtain a prepreg. A laminate and a printed wiring board are produced with the use of the prepreg. The prepreg is halogen free and is excellent in heat resistance, flame retardancy, punching processability, and insulation.